

BIOGRAPHY

Advanced Packaging Summit 2026



Name: Shinji Baba

Title/ Position: Vice President / Head of ATJ R&D Center

Company: Amkor Technology Japan, Inc.

Shinji Baba has been Vice President of the R&D Center at Amkor Technology Japan since 2025, leading next-generation semiconductor packaging R&D rooted in Japan's advanced manufacturing technologies, with a focus on power device packaging.

Baba began his career at Mitsubishi Electric Corporation in 1989, where he specialized in flip-chip and CSP packaging technologies. He later joined Renesas Technology Corporation in 2003 and Renesas Electronics Corporation in 2010, leading the development of advanced packaging technologies.

He holds a Master of Science degree in Precision Engineering from Osaka University, Japan.